

**AMENDMENTS TO THE CLAIMS:**

***Claims 1-32 (cancelled)***

33. (Previously presented) A polishing apparatus for polishing a workpiece, comprising:  
a table for providing a polishing surface;  
a first dresser having a contact surface for contacting said polishing surface during a first dressing operation;  
a second dresser having a contact surface for contacting said polishing surface during a second dressing operation;  
a sensor for measuring a profile of said polishing surface; and  
a controller for controlling a dressing process of said first dresser,  
wherein said first dresser and said second dresser are to perform said first dressing operation and said second dressing operation at different times, respectively.

34. (Previously presented) A polishing apparatus comprising:  
a polishing table having a polishing surface;  
a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece;  
at least two dressers for dressing said polishing surface, one of said at least two dressers comprising a diamond dresser; and  
a controller for performing an initial surface conditioning of said polishing surface with said one of said at least two dressers at a time prior to polishing of any workpiece so as to thinly shave said polishing surface, and for dressing said polishing surface with another of said at least two dressers after the workpiece has been polished.

35. (Previously presented) The polishing apparatus according to claim 34, wherein  
said one of said at least two dressers is for performing the initial surface conditioning of said polishing surface only at the time prior to polishing of any workpiece, and

said another of said at least two dressers is for dressing said polishing surface only after a workpiece has been polished.

36. (Previously presented) The polishing apparatus according to claim 34, wherein said at least two dressers are different in size relative to one another.

37. (Previously presented) A polishing apparatus comprising:  
a polishing table having a polishing surface;  
a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece; and  
at least two dressers for dressing said polishing surface,  
wherein one of said at least two dressers is to perform an initial surface conditioning of said polishing surface at a time prior to polishing of any workpiece, and another of said at least two dressers is for dressing said polishing surface after the workpiece has been polished,  
wherein at least one of said at least two dressers has a diameter greater than a diameter of the workpiece to be polished, and  
wherein at least one of said at least two dressers has a diameter smaller than the diameter of the workpiece to be polished.

38. (Previously presented) The polishing apparatus according to claim 34, wherein one of said at least two dressers is to move across said polishing surface while dressing said polishing surface.

39. (Previously presented) The polishing apparatus according to claim 34, wherein at least one of said at least two dressers is to dress said polishing surface while the workpiece is not being polished.

40. (Previously presented) The polishing apparatus according to claim 34, wherein said at least two dressers comprise diamond dressers.

41. (Previously presented) The polishing apparatus according to claim 34, wherein said another of said at least two dressers comprises a brush dresser.

42. (Previously presented) A polishing apparatus comprising:  
a polishing table having a polishing surface;  
a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece; and  
at least two dressers for dressing said polishing surface,  
wherein one of said at least two dressers is to perform an initial surface conditioning of said polishing surface at a time prior to polishing of any workpiece, and another of said at least two dressers is for dressing said polishing surface after the workpiece has been polished, and  
wherein one of said at least two dressers is to have at least one of its swing speed, rotational speed, and pressing load controlled based on a profile of a surface, to be polished, of the workpiece.

43. (Previously presented) A polishing apparatus comprising:  
a polishing table having a polishing surface;  
a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece; and  
at least two dressers for dressing said polishing surface,  
wherein one of said at least two dressers is to perform an initial surface conditioning of said polishing surface at a time prior to polishing of any workpiece, and another of said at least two dressers is for dressing said polishing surface after the workpiece has been polished, and  
wherein one of said at least two dressers is to have at least one of its swing speed, rotational speed, and pressing load controlled based on a profile of said polishing surface.

44. (Previously presented) A polishing apparatus comprising:  
a polishing table having a polishing surface;  
a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece;

at least two dressers for dressing said polishing surface, with one of said at least two dressers comprising a diamond dresser; and

a controller for performing a dressing operation with said one of said at least two dressers after a plurality of workpieces has been polished, and for dressing said polishing surface with another of said at least two dressers each time a workpiece has been polished,.

45. (Previously presented) The polishing apparatus according to claim 34, wherein said one of said at least two dressers is to dress said polishing surface when a polishing performance is not properly maintained.

46. (Previously presented) The polishing apparatus according to claim 45, wherein said one of said at least two dressers is to dress said polishing surface when the polishing performance is determined to not be properly maintained based on a profile of a surface, to be polished, of the workpiece not meeting a predetermined level requirement

47. (Previously presented) The polishing apparatus according to claim 34, further comprising:

an atomizer for spraying a fluid onto said polishing surface so as to remove a polishing waste present on said polishing surface.

48. (Previously presented) The polishing apparatus according to claim 47, wherein said atomizer is to spray a fluid composed of a mixture of gas and liquid.

49. (Previously presented) The polishing apparatus according to claim 47, wherein said atomizer is for spraying the fluid onto said polishing surface while the workpiece is not being polished.

50. (Previously presented) The polishing apparatus according to claim 47, wherein said atomizer is for spraying the fluid onto said polishing surface while said polishing surface is being dressed.